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## 100-W 48-V INPUT ISOLATED DC/DC CONVERTER

Check for Samples: PTQA430025, PTQA430033, PTQA420050

## **FEATURES**

- 100-W Output
- Input Voltage Range: 36 V to 75 V
- 92% Efficiency
- 1500 Vdc Isolation
- Fast Transient Response
- On/Off Control
- Overcurrent Protection
- Differential Remote Sense
- Adjustable Output Voltage
- Output Overvoltage Protection
- Over-Temperature Shutdown
- Undervoltage Lockout
- Standard 1/4-Brick Footprint
- UL Safety Agency Approval



#### DESCRIPTION

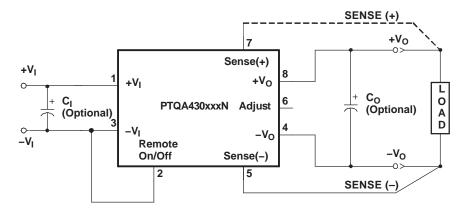
The PTQA series of power modules are single-output isolated DC/DC converters, housed in an industry standard quarter-brick package. These modules are rated up to 100W with a maximum load current of up to 30 A.

The PTQA series operates from a standard 48-V telecom central office (CO) supply and occupies only 3.3 in<sup>2</sup> of PCB area. The modules offer OEMs a compact and flexible high-output power source in an industry standard footprint. They are suitable for distributed power applications in both telecom and computing environments, and may be used for powering high-end microprocessors, DSPs, general purpose logic and analog.

Features include a remote On/Off control with optional logic polarity, an undervoltage lockout (UVLO), a differential remote sense, and an industry standard output voltage adjustment using an external resistor. Protection features include output overcurrent protection (OCP), overvoltage protection (OVP), and thermal shutdown (OTP).

The modules are fully integrated for stand-alone operation, and require no additional components.

#### STANDARD APPLICATION





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SLTS261C -MAY 2006-REVISED SEPTEMBER 2009

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **ORDERING INFORMATION**

For the most current package and ordering information, see the Package Option Addendum at the end of this datasheet, or see the TI website at www.ti.com.

#### **Table 1. PART NUMBERING SCHEME**

	Input Voltage	Output Current	Output Voltage	Enable	Electrical Options		Pin Style
PTQA	4	30	033	N	2	Α	D
	4 = 48 V	30 = 30A	025 = 2.5 V	N = Negative	2 = V <sub>O</sub> Adjust		D = Through-hole, Pb-free
		20 = 20A	033 = 3.3 V	P = Positive			S = SMD, SnPb solder ball
			050 = 5.0 V				Z = SMD, SnAgCu solder ball

#### **ABSOLUTE MAXIMUM RATING**

				UNIT
T <sub>A</sub>	Operating Temperature Range	Over V <sub>I</sub> Range	-40°C to 85°C <sup>(1)</sup>	
$V_{I,}$	Maximum lanut Valtana	80 V		
MAX	Maximum Input Voltage	Peak voltage for 100 ms duration	100 V	
			400 \\	
P <sub>O</sub> ,	Maximum Output Power		100 W	
MAX			75 W	
T <sub>S</sub>	Storage Temperature		-40°C to 125°C	
	Machaniaal Charle	Per Mil-STD-883, Method 2002.3 1 ms, 1/2	AD Suffix	250 G
	Mechanical Shock	Sine, mounted	AS or AZ Suffix	175 G
	Machaniaal Vibraniaa	Per Mil-STD-883, Method 2007.2 20-2000 Hz,	AD Suffix	15 G
	Mechanical Vibrarion	PCB mounted	AS or AZ Suffix	2.5 G
	Weight	30 grams		
	Flammability			

(1) See SOA curves or consult factory for appropriate derating.

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## **ELECTRICAL CHARACTERISTICS PTQA430025**

(Unless otherwise stated,  $T_A$  =25°C,  $V_I$  = 48 V,  $V_O$  = 2.5 V,  $C_O$  = 0  $\mu F$ , and  $I_O$  =  $I_O$ max)

	DADAMETED	TEST CO					
	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
Io	Output Current	Over V <sub>I</sub> range		0		30	Α
VI	Input Voltage Range	Over I <sub>O</sub> Range		36	48	75	V
V <sub>O</sub> tol	Set Point Voltage Tolerance				±1 <sup>(1)</sup>		%V <sub>O</sub>
Reg <sub>temp</sub>	Temperature Variation	-40°C >T <sub>A</sub> > 85°C			±1.15		%V <sub>O</sub>
Reg <sub>line</sub>	Line Regulation	Over V <sub>I</sub> range			±5		mV
Reg <sub>load</sub>	Load Regulation	Over I <sub>O</sub> range			±5		mV
$\Delta V_{o}$ tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T <sub>A</sub> > 85°C		±1.5	±3	%V <sub>O</sub>
$\Delta V_{ADJ}$	Output Adjust Range	P <sub>O</sub> ≤ 75 W		-20		10	%V <sub>O</sub>
η	Efficiency	I <sub>O</sub> = 50% I <sub>O</sub> max			91%		
$V_R$	V <sub>O</sub> Ripple (pk-pk)	20 MHz bandwidth			50	100	$mV_{pp}$
t <sub>tr</sub>	Transient Danness	0.1 A/µs slew rate, 50% to 75%	l <sub>O</sub> max		150		μs
$\Delta V_{tr}$	Transient Response	V <sub>O</sub> over/undershoot			25		mV
I <sub>TRIP</sub>	Overcurrent Threshold	Shutdown, followed by auto-rec	covery		41		Α
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V <sub>O</sub>	
OTP	Over Temperature Protection	Temperature Measurement at the nominal.		105		° C	
$f_s$	Switching Frequency	Over V <sub>I</sub> range		300		kHz	
UVLO	Lindon (oltografication)	V <sub>OFF</sub>	$V_I$ decreasing, $I_O = 6$ A		32.5		V
UVLO	Undervoltage Lockout	V <sub>HYS</sub>	Hysteresis		1.5		V
On/Off In	nput: Negative Enable						
$V_{IH}$	Input High Voltage	Deferenced to \/	2.4		Open <sup>(2)</sup>	V	
$V_{IL}$	Input Low Voltage	Referenced to -V <sub>I</sub>	-0.2		0.8	V	
I <sub>IL</sub>	Input Low Current				-0.3		mA
On/Off In	nput: Positive Enable						
$V_{IH}$	Input High Voltage	Deferenced to V		4.5		Open <sup>(2)</sup>	V
$V_{IL}$	Input Low Voltage	Referenced to -V <sub>I</sub>		-0.2		0.8	V
$I_{\rm IL}$	Input Low Current			-0.5		mA	
I <sub>ISB</sub>	Standby Input Current	Output disabled (pin 2 status se		37		mA	
C <sub>I</sub>	External Input Capacitance	Between +V <sub>I</sub> and -V <sub>I</sub>		100		μF	
Co	External Output Capacitance	external Output Between +V <sub>O</sub> and -V <sub>O</sub>				30000	μF
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc
	Isolation Capacitance	Input-to-output			1200		pF
	Isolation Resistance	Input-to-output		10			МΩ

 <sup>(1)</sup> If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.
 (2) The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.

NSTRUMENTS

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#### **ELECTRICAL CHARACTERISTICS PTQA430033**

(Unless otherwise stated,  $T_A$  =25°C,  $V_I$  = 48 V,  $V_O$  = 3.3 V,  $C_O$  = 0  $\mu F$ , and  $I_O$  =  $I_O$ max)

	DADAMETED	TEST OF	ONDITIONS				
	PARAMETER	IESI CC	ONDITIONS	MIN	TYP	MAX	UNIT
Io	Output Current	Over V <sub>I</sub> range		0		30	Α
VI	Input Voltage Range	Over I <sub>O</sub> Range		36	48	75	V
V <sub>O</sub> tol	Set Point Voltage Tolerance				±1 <sup>(1)</sup>		%V <sub>O</sub>
Reg <sub>temp</sub>	Temperature Variation	-40°C >T <sub>A</sub> > 85°C			±1.15		%V <sub>O</sub>
Reg <sub>line</sub>	Line Regulation	Over V <sub>I</sub> range			±5		mV
Reg <sub>load</sub>	Load Regulation	Over I <sub>O</sub> range			±5		mV
ΔV <sub>o</sub> tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T <sub>A</sub> > 85°C		±1.5	±3	%V <sub>O</sub>
$\Delta V_{ADJ}$	Output Adjust Range	P <sub>O</sub> ≤ 100 W		-20		10	%V <sub>O</sub>
η	Efficiency	I <sub>O</sub> = 50% I <sub>O</sub> max			92%		
$V_R$	V <sub>O</sub> Ripple (pk-pk)	20 MHz bandwidth			50	100	$mV_{pp}$
t <sub>tr</sub>	Transient Danners	0.1 A/µs slew rate, 50% to 75%	I <sub>O</sub> max		150		μs
$\Delta V_{tr}$	Transient Response	V <sub>O</sub> over/undershoot			33		mV
I <sub>TRIP</sub>	Overcurrent Threshold	Shutdown, followed by auto-rec	covery		41		Α
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V <sub>O</sub>	
OTP	Over Temperature Protection	Temperature Measurement at the nominal.		105		°C	
$f_s$	Switching Frequency	Over V <sub>I</sub> range			300		kHz
UVLO	Lindom rolto ao Lookovit	V <sub>OFF</sub>	V <sub>I</sub> decreasing, I <sub>O</sub> = 6 A		32.5		V
0 VLO	Undervoltage Lockout	V <sub>HYS</sub>	Hysteresis		1.5		<b>v</b>
On/Off Ir	nput: Negative Enable						
$V_{\text{IH}}$	Input High Voltage	Referenced to -V <sub>I</sub>	2.4		Open <sup>(2)</sup>	V	
$V_{IL}$	Input Low Voltage	Neierenced to -v		-0.2		0.8	<b>v</b>
I <sub>IL</sub>	Input Low Current				-0.3		mA
On/Off Ir	nput: Positive Enable						
$V_{IH}$	Input High Voltage	Potoropood to V		4.5		Open <sup>(2)</sup>	V
$V_{IL}$	Input Low Voltage	Referenced to -V <sub>I</sub>		-0.2		0.8	<b>v</b>
$I_{\text{IL}}$	Input Low Current				-0.5		mA
I <sub>Isb</sub>	Standby Input Current	Output disabled (pin 2 status se		42		mA	
C <sub>I</sub>	External Input Capacitance	Between +V <sub>I</sub> and -V <sub>I</sub>		100		μF	
C <sub>O</sub>	External Output Capacitance		0		30000	μF	
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc
	Isolation Capacitance	Input-to-output			1200		pF
	Isolation Resistance	Input-to-output		10			ΜΩ

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 <sup>(1)</sup> If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.
 (2) The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.



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## **ELECTRICAL CHARACTERISTICS PTQA420050**

(Unless otherwise stated,  $T_A$  =25°C,  $V_I$  = 48 V,  $V_O$  = 5.0 V,  $C_O$  = 0  $\mu F$ , and  $I_O$  =  $I_O$ max)

	PARAMETER	TEST CO	PTQA420050				
	FARAIVIE I EK	151 00	MIN	TYP	MAX	UNIT	
Io	Output Current	Over V <sub>I</sub> range		0		20	Α
VI	Input Voltage Range	Over I <sub>O</sub> Range		36	48	75	V
V <sub>O</sub> tol	Set Point Voltage Tolerance				±1 <sup>(1)</sup>		%V <sub>O</sub>
Reg <sub>temp</sub>	Temperature Variation	-40°C >T <sub>A</sub> > 85°C			±1.15		%V <sub>O</sub>
Reg <sub>line</sub>	Line Regulation	Over V <sub>I</sub> range			±5		mV
Reg <sub>load</sub>	Load Regulation	Over I <sub>O</sub> range			±5		mV
$\Delta V_{o}$ tot	Total Output Voltage Variation	Includes set-point, line, load, -4	40°C >T <sub>A</sub> > 85°C		±1.5	±3	%V <sub>O</sub>
$\Delta V_{ADJ}$	Output Adjust Range	P <sub>O</sub> ≤ 100 W		-20		10	%V <sub>O</sub>
η	Efficiency	I <sub>O</sub> = 50% I <sub>O</sub> max			92.5%		
$V_R$	V <sub>O</sub> Ripple (pk-pk)	20 MHz bandwidth			50	100	$mV_{pp}$
t <sub>tr</sub>	Transient Despense	0.1 A/µs slew rate, 50% to 75%	o I <sub>O</sub> max		100		μs
$\Delta V_{tr}$	Transient Response	V <sub>O</sub> over/undershoot			50		mV
I <sub>TRIP</sub>	Overcurrent Threshold	Shutdown, followed by auto-red	covery		29		Α
OVP	Output Overvoltage Protection	Output shutdown and latch off		120		%V <sub>O</sub>	
OTP	Over Temperature Protection	Temperature Measurement at t nominal.		105		° C	
fs	Switching Frequency	Over V <sub>I</sub> range			300		kHz
111/1/0	l la deminita de la calcació	V <sub>OFF</sub>	V <sub>I</sub> decreasing, I <sub>O</sub> = 6 A		32.5		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
UVLO	Undervoltage Lockout	V <sub>HYS</sub>	Hysteresis		1.5		V
On/Off Ir	nput: Negative Enable						
$V_{IH}$	Input High Voltage	Deferenced to \/		2.4		Open <sup>(2)</sup>	V
$V_{IL}$	Input Low Voltage	Referenced to -V <sub>I</sub>	-0.2		0.8	V	
I <sub>IL</sub>	Input Low Current				-0.3		mA
On/Off Ir	nput: Positive Enable						
$V_{IH}$	Input High Voltage	Defended to V		4.5		Open <sup>(2)</sup>	V
$V_{IL}$	Input Low Voltage	Referenced to -V <sub>I</sub>		-0.2		0.8	V
$I_{\rm IL}$	Input Low Current				-0.5		mA
I <sub>Isb</sub>	Standby Input Current	Output disabled (pin 2 status se		58		mA	
C <sub>I</sub>	External Input Capacitance	Between +V <sub>I</sub> and -V <sub>I</sub>		100		μF	
Co	External Output Capacitance	Between +V <sub>O</sub> and -V <sub>O</sub>	0		30000	μF	
	Isolation Voltage	Input-to-output and input-to-cas	se	1500			Vdc
	Isolation Capacitance	Input-to-output			1200		pF
	Isolation Resistance	Input-to-output		10			ΜΩ

<sup>(1)</sup> If Sense(-) is not used, pin 5 must be connected to pin 4 for optimum output voltage accuracy.

<sup>(2)</sup> The Remote On/Off input has an internal pull-up and may be controlled with an open collector (drain) interface. An open circuit correlates to a logic high. Consult the application notes for interface considerations.

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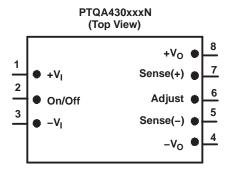
INSTRUMENTS

#### PIN DESCRIPTIONS

- + $V_i$ : The positive input for the module with respect to  $-V_i$ . When powering the module from a -48-V telecom central office supply, this input is connected to the primary system ground.
- -V<sub>i</sub>: The negative input supply for the module, and the 0 VDC reference for the Remote On/Off input. When powering the module from a +48-V supply, this input is connected to the 48-V return.

**Remote On/Off:** This input controls the On/Off status of the output voltage. It is either driven low  $(-V_1)$  potential, or left open-circuit. For units identified with the NEN option, applying a logic low to this pin will enable the output. And for units identified with the PEN option, the output will be disabled.

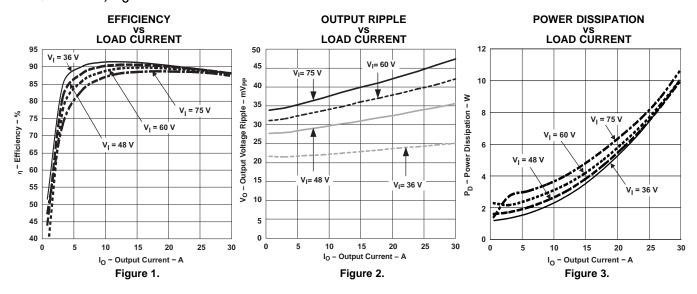
- $V_0$  Adjust: Allows the output voltage to be trimmed by up or down between +10% and -20% of its nominal value. The adjustment method uses a single external resistor. Connecting the resistor between  $V_0$  Adjust and  $-V_0$  adjusts the output voltage lower, and placing it between  $V_0$  Adjust and  $+V_0$  adjusts the output higher. The calculations for the resistance value follows industry standard formulas. For further information consult the application note on output voltage adustment.
- **+V<sub>O</sub>:** The positive power output with respect to  $-V_O$ , which is DC isolated from the input supply pins. If a negative output voltage is desired,  $+V_O$  should be connected to the secondary circuit common and the output taken from  $-V_O$ .
- $-\mathbf{V}_{O}$ : The negative power output with respect to  $+\mathbf{V}_{O}$ , which is DC isolated from the input supply pins. This output is normally connected to the secondary circuit common when a positive output voltage is desired.
- **Sense(+):** Provides the converter with an output sense capability to regulate the set-point voltage directly at the load. When used with Sense(-), the regulation circuitry will compensate for voltage drop between the converter and the load. The pin may be left open circuit, but connecting it to +V<sub>O</sub> improves load regulation.
- **Sense(–):** Provides the converter with an output sense capability when used in conjunction with Sense(+) input. For optimum output voltage accuracy this pin should always be connected to  $-V_0$ .



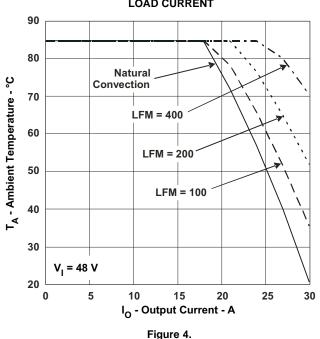


#### TYPICAL CHARACTERISTICS

## PTQA430025, $V_0 = 2.5 V^{(1)}$ (2)



# AMBIENT TEMPERATURE VS LOAD CURRENT

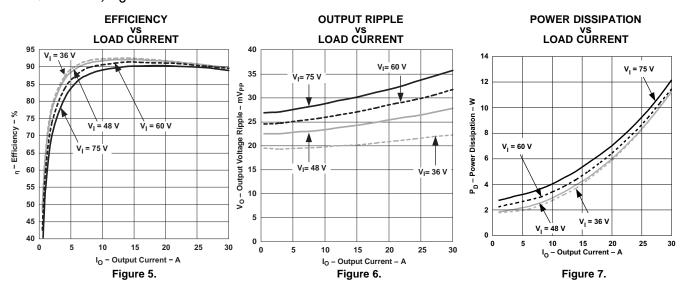


- (1) All data listed in Figure 1, Figure 2, and Figure 3 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm x 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 4.

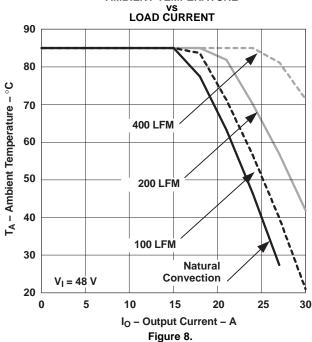


#### TYPICAL CHARACTERISTICS

# PTQA430033, $V_0 = 3.3 V^{(1)}$ (2)



#### **AMBIENT TEMPERATURE**



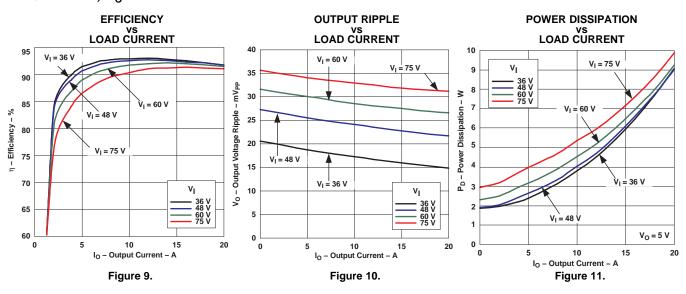
- (1) All data listed in Figure 5, Figure 6, and Figure 7 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm × 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 8.

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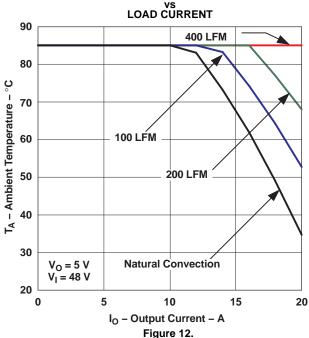
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#### TYPICAL CHARACTERISTICS

# PTQA420050, $V_0 = 5.0 V^{(1)}$ (2)



#### AMBIENT TEMPERATURE



- (1) All data listed in Figure 9, Figure 10, and Figure 11 have been developed from actual products tested at 25°C. This data is considered typical data for the dc-dc converter.
- (2) The temperature derating curves represent operating conditions at which internal components are at or below manufacturer's maximum rated operating temperature. Derating limits apply to modules soldered directly to a 100–mm x 100–mm, double-sided PCB with 2 oz. copper. For surface mount packages, multiple vias (plated through holes) are required to add thermal paths around the power pins. Please refer to the mechanical specification for more information. Applies to Figure 12.

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#### APPLICATION INFORMATION

## Operating Features and System Considerations for the PTQA Series of DC/DC Converters

#### **Overcurrent Protection**

To protect against load faults, these converters incorporate output overcurrent protection. Applying a load to the output that exceeds the converter's overcurrent threshold (see applicable specification) will cause the output voltage to momentarily fold back, and then shut down. Following shutdown the module will periodically attempt to automatically recover by initiating a soft-start power-up. This is often described as a hiccup mode of operation, whereby the module continues in the cycle of successive shutdown and power up until the load fault is removed. Once the fault is removed, the converter automatically recovers and returns to normal operation.

#### **Output Overvoltage Protection**

Each converter incorporates protection circuitry that continually senses for an output overvoltage (OV) condition. The OV threshold is set approximately 20% higher than the nominal output voltage. If the converter output voltage exceeds this threshold, the converter is immediately shut down and remains in a latched-off state. To resume normal operation the converter must be actively reset. This can only be done by momentarily removing the input power to the converter. For fail-safe operation and redundancy, the OV protection uses circuitry that is independent of the converter's internal feedback loop.

#### **Overtemperature Protection**

Overtemperature protection is provided by an internal temperature sensor, which closely monitors the temperature of the converter's printed circuit board (PCB). If the sensor exceeds a temperature of approximately 105°C, the converter will shut down. The converter will then automatically restart when the sensed temperature drops back to approximately 95°C. When operated outside its recommended thermal derating envelope (see data sheet SOA curves), the converter will typically cycle on and off at intervals from a few seconds to one or two minutes. This is to ensure that the internal components are not permanently damaged from excessive thermal stress.

#### **Undervoltage Lockout**

The Undervoltage lockout (UVLO) is designed to prevent the operation of the converter until the input voltage is at the minimum input voltage. This prevents high start-up current during normal power-up of the converter, and minimizes the current drain from the input source during low input voltage conditions. The UVLO circuitry also overrides the operation of the Remote On/Off control.

#### **Primary-Secondary Isolation**

These converters incorporate electrical isolation between the input terminals (primary) and the output terminals (secondary). All converters are production tested to a withstand voltage of 1500 VDC. This specification complies with UL60950 and EN60950 requirements. This allows the converter to be configured for either a positive or negative input voltage source. The data sheet Pin Descriptions section provides guidance as to the correct reference that must be used for the external control signals.

#### **Input Current Limiting**

The converter is not internally fused. For safety and overall system protection, the maximum input current to the converter must be limited. Active or passive current limiting can be used. Passive current limiting can be a fast acting fuse. A 125-V fuse, rated no more than 10 A, is recommended. Active current limiting can be implemented with a current limited *Hot-Swap* controller.

#### **Thermal Considerations**

Airflow may be necessary to ensure that the module can supply the desired load current in environments with elevated ambient temperatures. The required airflow rate may be determined from the Safe Operating Area (SOA) thermal derating chart (see typical characteristics).

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## Not Recommended for New Designs



# PTQA430025, PTQA430033, PTQA420050

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#### **Differential Remote Sense**

The remote sense pins allows the converter to precisely regulate the DC output voltage at a remote location. This might be a power plane on an inner layer of the host PCB. Connecting Sense(+) directly to  $+V_O$ , and Sense(-) to  $-V_O$  will improve output voltage accuracy. In the event that the sense pins are left open-circuit, an internal  $10-\Omega$  resistor between each sense pin and its corresponding output prevents an excessive rise in the output voltage. For practical reasons, the amount of IR voltage compensation should be limited to 0.5 V maximum.

The remote sense feature is designed to compensate for limited amounts of *IR* voltage drop. It is **not** intended to compensate for the forward drop of a non-linear or frequency dependent components that may be placed in series with the converter output. Examples of such components include OR-ing diodes, filter inductors, ferrite beads, and fuses. Enclosing these components with the remote sense connections effectively places them inside the regulation control loop, which can affect the stability of the regulator.

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## Using the Remote On/Off Function on the PTQA Series of DC/DC Converters

For applications requiring output voltage On/Off control, the PTQA series of DC/DC converters incorporate a *Remote On/Off* control (pin 2). This feature can be used to switch the module off without removing the applied input source voltage. When placed in the *Off* state, the standby current drawn from the input source is typically reduced to 3 mA.

## **Negative Output Enable (NEN)**

Models using the negative enable option, the *Remote On/Off* (pin 2) control must be driven to a logic low voltage for the converter to produce an output. This is accomplished by either permanently connecting pin 2 to  $-V_1$  (pin 3), or driving it low with an external control signal. Table 2 shows the input requirements of pin 2 for those modules with the *NEN* option.

Table 2. On/Off Control Requirements for Negative Enable

	PARAMETER	MIN	TYP	MAX
$V_{IH}$	Disable	2.4 V		20 V
$V_{IL}$	Enable	-0.2 V		0.8 V
V <sub>o/c</sub>	Open-Circuit		9 V	15 V
$I_{\parallel}$	Pin 2 at -V <sub>1</sub>			−0.75 mA

#### **Positive Output Enable (PEN)**

For those models with the positive enable (PEN) option, leaving pin 2 open circuit, (or driving it to an equivalent logic high voltage), will enable the converter output. This allows the module to produce an output voltage whenever a valid input source voltage is applied to  $+V_1$  with respect to  $-V_1$ . If a logic-low signal is then applied to pin 2 the converter output is disabled. Table 3 gives the input requirements of pin 2 for modules with the *PEN* option.

Table 3. On/Off Control Requirements for Positive Enable

	PARAMETER	MIN	TYP	MAX
$V_{IH}$	Enable	4.5 V		20 V
$V_{IL}$	Disable	-0.2 V		0.8 V
V <sub>o/c</sub>	Open-Circuit		5 V	7 V
I	Pin 2 at –V <sub>I</sub>			–0.5 mA

#### Notes:

- 1. The Remote On/Off control uses  $-V_1$  (pin 3) as its ground reference. All voltages are with respect to  $-V_1$ .
- 2. An open-collector device (preferably a discrete transistor) is recommended. A pull-up resistor is not required. If one is added the pull-up voltage should not exceed 20 V.

**Caution**: Do not use a pull-resistor to  $+V_1$  (pin 1). The remote On/Off control has a maximum input voltage of 20 V. Exceeding this voltage will overstress, and possibly damage, the converter.

- 3. The *Remote On/Off* pin may be controlled with devices that have a totem-pole output. This is provided the output high level voltage (V<sub>OH</sub>) meets the module's minimum V<sub>IH</sub> specified in Table 2. If a TTL gate is used, a pull-up resistor may be required to the logic supply voltage.
- 4. The converter incorporates an *undervoltage lockout* (UVLO). The UVLO keeps the converter off until the input voltage is close to the minimum specified operating voltage. This is regardless of the state of the *Remote On/Off* control. Consult the product specification for the UVLO input voltage thresholds.

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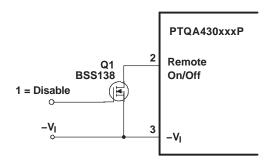


Figure 13. Recommended Control or Remote On/Off Input

**Turn-On:** With a valid input source voltage applied, the converter produces a regulated output voltage within 75 ms of the output being enabled. Figure 14 shows the output response of the PTQA430033P following the removal of the logic-low signal from the *Remote On/Off* (pin 2); see Figure 13. This corresponds to the drop in Q1  $V_{GS}$  in Figure 14. Although the rise-time of the output voltage is short (<10 ms), the indicated delay time will vary depending upon the input voltage and the module's internal timing. The waveforms were measured with 48 VDC input voltage, and a 10-A resistive load.

**Turn-Off Time:** When a valid input source is removed or if the *Remote On/Off* (pin 2) is used to disable the output, with no external output capacitance, the module powers down within 200 μs. Figure 15 shows that, during power down, there is a small undershoot, typically less than 300 mV (or less than a diode drop). If used to supply processor I/O voltages, the low undershoot ensures the parasitic diodes do not conduct current and potentially cause damage to external circuitry.

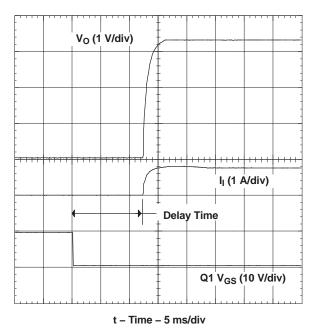


Figure 14. Power Up

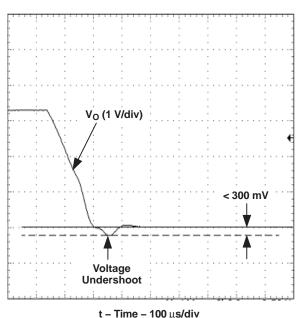


Figure 15. Power Down



## Adjusting the Output Voltage of the 100-W Rated PTQA Series of Isolated DC/DC Converters

The output voltage adjustment of the PTQA series of isolated DC/DC converters follows the standard adopted by popular 1/4-brick DC/DC converters. Adjustment is accomplished with a single external resistor that can adjust the output voltage from –20% to +10% of the nominal set-point voltage. The placement of the resistor determines the direction of adjustment, up or down, and the value of the magnitude of adjustment.

**Adjust Up:** To increase the output voltage add a resistor, R1, between  $V_0$  Adjust (pin 6) and Sense(+) (pin 7).

**Adjust Down:** Add a resistor, (R2), between  $V_O$  Adjust (pin 6) and Sense(–) (pin 5).

Refer to Figure 16 for the placement of the required resistor, R1 or (R2).

The values of R1 [adjust up], and (R2) [adjust down], can be calculated using the following formulas or selected from Table 4.

$$R1 = \frac{5.11 \text{ V}_{\text{O}} (100 + \Delta\%)}{1.225 \Delta\%} - \frac{511}{\Delta\%} - 10.22 \text{ (k}\Omega)$$
(1)

$$(R2) = 5.11 \frac{100}{\Delta\%} - 10.22 \quad (k\Omega)$$
 (2)

Where:

 $\Delta$ % = Amount of adjustment in %

V<sub>O</sub> = Original set-point voltage

#### Notes:

- 1. Use only a single 1% resistor in either the R1 or (R2) location. Place the resistor as close to the converter as possible.
- 2. If the output voltage is increased, the maximum load current must be derated according to the following equation.

$$I_{O}(max) = \frac{V_{O} \times I_{O}(rated)}{V_{A}}$$
(3)

Where:

V<sub>O</sub> = Original set-point voltage

V<sub>A</sub> = Adjusted output voltage (measured between pins 8 and 4)

In any instance, the load current must not exceed the converter's maximum rated output current of 30 A.

3. The overvoltage threshold is fixed, and is set approximately 20% above the nominal output voltage. Adjusting the output voltage higher reduces the voltage margin between the adjusted output voltage and the overvoltage (OV) protection threshold. This could make the module sensitive to OV fault detection, as a result of random noise and load transients.

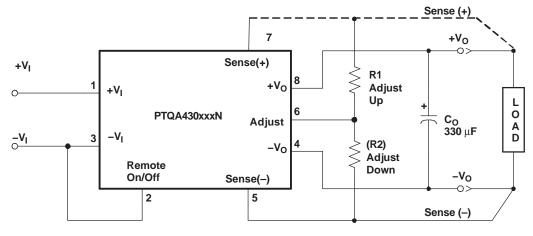


Figure 16.



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## **Table 4. Standard Adjustment Resistor Values**

	Adjust	ted Output Volta	age (V)		Trim-Up R <sub>AD</sub>	J	Tı	rim-Down R	\DJ
V <sub>O</sub> (nom) % Adjust (V)	5.0 V	3.3 V	2.5 V	5.0 V R1 (kΩ)	3.3 V R1 (kΩ)	2.5 V R1 (kΩ)	5.0 V R2 (kΩ)	3.3 V R2 (kΩ)	2.5 V R2 (kΩ)
+10	5.50	3.630	2.750	169	90.9	53.6	-	-	-
+ 9	5.45	3.597	2.725	187	100	59.0	-	-	-
+ 8	5.40	3.564	2.700	205	113	66.5	-	-	-
+ 7	5.35	3.531	2.675	237	127	76.8	-	-	-
+ 6	5.30	3.498	2.650	274	147	88.7	-	-	-
+ 5	5.25	3.465	2.625	324	178	107	-	-	-
+ 4	5.20	3.432	2.600	402	221	133	-	-	-
+ 3	5.15	3.399	2.575	536	294	178	-	-	-
+ 2	5.10	3.366	2.550	787	432	267	-	-	-
+ 1	5.05	3.333	2.525	1580	866	536	-	-	-
0	5.00	3.300	2.500	Open	Open	Open	-	-	-
-1	4.95	3.267	2.475	-	-	-	499	499	499
-2	4.90	3.234	2.450	-	-	-	243	243	243
-3	4.85	3.201	2.425	-	-	-	158	158	158
-4	4.80	3.168	2.400	-	-	-	118	118	118
-5	4.75	3.135	2.375	-	-	-	90.9	90.9	90.9
-6	4.70	3.102	2.350	-	-	-	75	75	75
-7	4.65	3.069	2.325	-	-	-	63.4	63.4	63.4
-8	4.60	3.036	2.300	-	-	-	53.6	53.6	53.6
-9	4.55	3.003	2.275	-	-	-	46.4	46.4	46.4
-10	4.50	2.970	2.250	-	-	-	41.2	41.2	41.2
-11	4.45	2.937	2.225	-	-	-	36.5	36.5	36.5
-12	4.40	2.904	2.200	-	-	-	32.4	32.4	32.4
-13	4.35	2.871	2.175	-	-	-	28.7	28.7	28.7
-14	4.30	2.838	2.150	-	-	-	26.1	26.1	26.1
-15	4.25	2.805	2.125	-	-	-	23.7	23.7	23.7
-16	4.20	2.772	2.100	-	-	-	21.5	21.5	21.5
-17	4.15	2.739	2.075	-	-	-	19.6	19.6	19.6
-18	4.10	2.706	2.050	-	-	-	18.2	18.2	18.2
-19	4.05	2.673	2.025	-	-	-	16.5	16.5	16.5
-20	4.00	2.640	2.000	-	-	-	15.4	15.4	15.4

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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PTQA420050N2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		
PTQA420050N2AS	NRND	Surface Mount Module	EAQ	8	9	TBD	SNPB	Level-1-235C-UNLIM/ Level-3-260C-168HRS	-40 to 85		
PTQA420050N2AZ	NRND	Surface Mount Module	BAQ	8	9	Pb-Free (RoHS)	SNAGCU	Level-3-260C-168 HR	-40 to 85		
PTQA420050P2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		
PTQA420050P2AS	NRND	Surface Mount Module	EAQ	8	9	TBD	SNPB	Level-1-235C-UNLIM/ Level-3-260C-168HRS	-40 to 85		
PTQA420050P2AZ	NRND	Surface Mount Module	BAQ	8	9	Pb-Free (RoHS)	SNAGCU	Level-3-260C-168 HR	-40 to 85		
PTQA430025N2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		
PTQA430025P2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		
PTQA430033N2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		
PTQA430033P2AD	NRND	Through- Hole Module	EAP	8	9	Pb-Free (RoHS)	SN	N / A for Pkg Type	-40 to 85		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

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**TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



## PACKAGE OPTION ADDENDUM

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- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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- NOTES:
- A. All linear dimensions are in inches (mm).
- This drawing is subject to change without notice.
- C. 2 place decimals are  $\pm 0.020$  ( $\pm 0.51$ mm).
- D. 3 place decimals are  $\pm 0.010$  ( $\pm 0.25$ mm).
- E. Recommended keep out area for user components.
- Pins are 0.060" (1,52) diameter with 0.125" (3,20) diameter standoff shoulder.
- G. All pins: Material Copper Alloy
  Finish Tin (100%) over Nickel plate

  H. Pins are 0.040" (1,02) diameter with
  0.070" (1,78) diameter standoff shoulder.



#### EAQ (R-PDSS-B8) DOUBLE SIDED MODULE - 2.22 (56,39) 0.495 0.110 (12,57)- 2.000 (50,80) (2,79)MAX. Note J 0.43 (10,90)8 • Solder Ball 0.300 Ø0.040 (1,02) (7,62) 0.600 1.45 0.150 8 Places (36,83)• 0.600 (15,24) - (3,81) 4 Places See Note I. • **•** 3 4 • TOP VIEW SIDE VIEW 2.260 (57,40) 0.130. - 2.000 (50,80) (3,30)Lowest Component 0.010 MIN. (0,25) 0.45 Bottom side (11,43)Clearance 0.300 (7,62) 0.600 0.150 (15,24) 1.490 — (3,81) 4 Places (37,85)Host Board Ø0.085 (2,16) 8 Places See Note F, G & H Note E -0.472 (12,00)PCB Layout MAX. 4207563/A 12/05

NOTES: Α. All linear dimensions are in inches (mm).

- This drawing is subject to change without notice.
- 2 place decimals are  $\pm 0.020$  ( $\pm 0,51$ mm). 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
- Recommended keep out area for user components.
- Power pin connection should utilize four or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).
- H. Pad type: Solder mask defined.
- I. All pins: Material Copper Alloy
  Finish Tin (100%) over Nickel plate
  Solder Ball See product data sheet.

J. Dimension prior to reflow solder.



#### DOUBLE SIDED MODULE BAQ (R-PDSS-B8) - 2.22 (56,39) 0.495 0.110 (12,57)2.000 (50,80) (2,79)MAX. Note J 0.43 (10,90)8 • Solder Ball 0.300 Ø0.040 (1,02) (7,62) 0.600 1.45 PX000000X 0.150 8 Places (36,83)• 0.600 (15,24) — (3,81) 4 Places See Note I. xxx **₹** • DATE CODE **•** 3 4 • TOP VIEW SIDE VIEW 2.260 (57,40) 0.130. - 2.000 (50,80) (3,30)Lowest Component 0.010 MIN. (0,25) 0.45 Bottom side (11,43)Clearance 0.300 (7,62) 0.600 0.150 (15,24) 1.490 — (3,81) 4 Places (37,85)Host Board Ø0.085 (2,16) 8 Places See Note F, G & H Note E -0.472 (12,00)PCB Layout

NOTES: Α. All linear dimensions are in inches (mm).

- This drawing is subject to change without notice.
- 2 place decimals are  $\pm 0.020$  ( $\pm 0,51$ mm). 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
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- Power pin connection should utilize four or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).
- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16). Paste screen thickness: 0.006 (0,15).

MAX.

- H. Pad type: Solder mask defined.
- I. All pins: Material Copper Alloy Finish Tin (100%) over Nickel plate Solder Ball 96.5 Sn/3.0 Ag/0.5 Cu

4207714/A 02/06

J. Dimension prior to reflow solder.



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